

D1153-G60S-4 PRELIMINARY High Power MIR AO Modulator



0521

The D1153 has been developed specifically to operate with high power unpolarized mid-IR fibre lasers. Typical applications include material processing, marking and engraving at 2um. Adopting the same techniques as applied to our very high power IR devices, these units are designed to minimize thermal lensing and reduce beam degradation at high optical powers.

SPECFICATIONS (TYPICAL)

Operating Wavelength: Interaction Material: Active Aperture:

Centre Frequency (fc): FM Bandwidth:

Diffraction Efficiency: RF Power for Max. D/E Static Insertion Loss: Maximum Optical Power:

Bragg Angle at 2um: Separation Angle at 2um: Scan Angle at 2um:

Laser Polarization:

Water Cooling (Minimum):

Any

1.9 - 2.1µm *

< 6 Watts total

< 6% (2.1um)

16.9 mrad (60MHz)

33.8 mrad (60MHz) 14.0 mrad (25MHz sweep)

5mmH x 14.5mmW

> 85% at fc, 90% typical

200 Watts, 3mm dia. Gaussian beam

Germanium

60MHz

25MHz

1 Liter/Min. @ < 20°C

> 80% across scan

 Modulation performance
 : 3 mm beam diameter

 Optical Rise Time
 0.83usec

<u>Deflector Performance</u>: 3 x 14.5mm beam Diffraction Efficiency Access Time: Resolution:

Deflector Drive Electronics:

RFA3060-2-4

4.0usec

100

The RFA360/2 exhibits progressive phase shifting across two RF output channels. This technique compensates for the variation in efficiency across the scan due to input Bragg angle errors

* Optional designs are available for other wavelengths in the 2.5μm - 11.2μm range.

ALL SPECIFICATIONS SUBJECT TO CHANGE WITHOUT NOTICEISOMET CORP, 10342 Battleview Parkway, Manassas, VA 20109, USA.Tel: (703) 321 8301Fax: (703) 321 8546E-mail: ISOMET@ ISOMET.COMWeb Page: WWW.ISOMET.COM

Quality Assured. In-house: Crystal Growth, Optical Polishing, A/R coating, Vacuum Bonding



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